



MICROCHIP

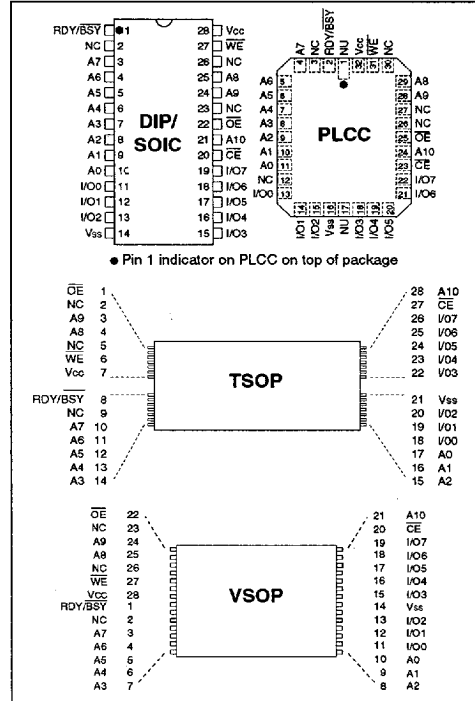
# 28C17A

## 16K (2K x 8) CMOS EEPROM

### FEATURES

- Fast Read Access Time—150 ns
- CMOS Technology for Low Power Dissipation
  - 30 mA Active
  - 100  $\mu$ A Standby
- Fast Byte Write Time—200  $\mu$ s or 1 ms
- Data Retention >10 years
- High Endurance - Minimum  $10^4$  Erase/Write Cycles
- Automatic Write Operation
  - Internal Control Timer
  - Auto-Clear Before Write Operation
  - On-Chip Address and Data Latches
- Data Polling; Ready/Busy
- Chip Clear Operation
- Enhanced Data Protection
  - Vcc Detector
  - Pulse Filter
  - Write Inhibit
- Electronic Signature for Device Identification
- 5-Volt-Only Operation
- Organized 2Kx8 JEDEC Standard Pinout
  - 28 Pin Dual-In-Line Package
  - 32-Pin Chip Carrier (Leadless or Plastic)
  - 28-Pin Thin Small Outline Package (TSOP) 8x20mm
  - 28-Pin Very Small Outline Package (VSOP) 8x13.4mm
- Available for Extended Temperature Ranges:
  - Commercial: 0°C to +70°C
  - Industrial: -40°C to +85°C

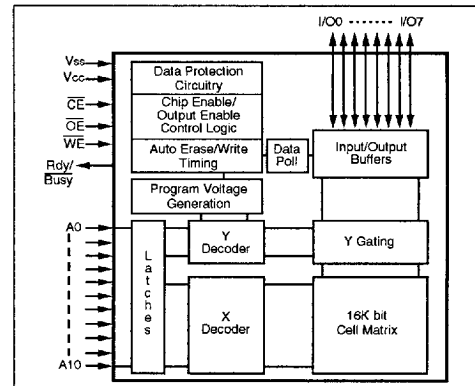
### PACKAGE TYPE



### DESCRIPTION

The Microchip Technology Inc. 28C17A is a CMOS 16K non-volatile electrically Erasable PROM. The 28C17A is accessed like a static RAM for the read or write cycles without the need of external components. During a "byte write", the address and data are latched internally, freeing the microprocessor address and data bus for other operations. Following the initiation of write cycle, the device will go to a busy state and automatically clear and write the latched data using an internal control timer. To determine when the write cycle is complete, the user has a choice of monitoring the Ready/Busy output or using Data polling. The Ready/Busy pin is an open drain output, which allows easy configuration in wired-or systems. Alternatively, Data polling allows the user to read the location last written to when the write operation is complete. CMOS design and processing enables this part to be used in systems where reduced power consumption and reliability are required. A complete family of packages is offered to provide the utmost flexibility in applications.

### BLOCK DIAGRAM



## 1.0 ELECTRICAL CHARACTERISTICS

### 1.1 MAXIMUM RATINGS\*

Vcc and input voltages w.r.t. Vss ..... -0.6V to + 6.25V  
 Voltage on  $\overline{OE}$  w.r.t. Vss ..... -0.6V to +13.5V  
 Voltage on A9 w.r.t. Vss ..... -0.6V to +13.5V  
 Output Voltage w.r.t. Vss ..... -0.6V to Vcc+0.6V  
 Storage temperature ..... -65°C to +125°C  
 Ambient temp. with power applied ..... -50°C to +95°C

\*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

Name	Function
A0 - A10	Address Inputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
$\overline{WE}$	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
RDY/Busy	Ready/Busy
Vcc	+5V Power Supply
Vss	Ground
NC	No Connect; No Internal Connection
NU	Not Used; No External Connection is Allowed

TABLE 1-2: READ/WRITE OPERATION DC CHARACTERISTICS

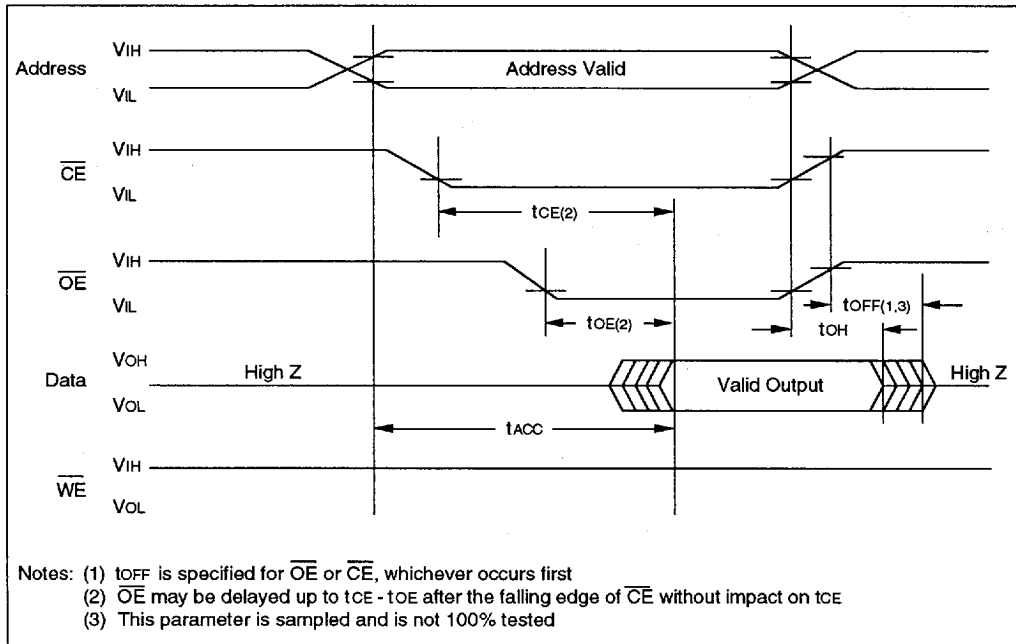
Vcc = +5V ±10% Commercial (C): Tamb = 0°C to +70°C Industrial (I): Tamb = -40°C to +85°C						
Parameter	Status	Symbol	Min	Max	Units	Conditions
Input Voltages	Logic '1'	V <sub>IH</sub>	2.0	Vcc+1	V	
	Logic '0'	V <sub>IL</sub>	-0.1	0.8	V	
Input Leakage	—	I <sub>LI</sub>	-10	10	µA	V <sub>IN</sub> = -0.1V to Vcc +1
Input Capacitance	—	C <sub>IN</sub>	—	10	pF	V <sub>IN</sub> = 0V; Tamb = 25°C; f = 1 MHz
Output Voltages	Logic '1'	V <sub>OH</sub>	2.4		V	I <sub>OH</sub> = -400 µA I <sub>OL</sub> = 2.1 mA
	Logic '0'	V <sub>OL</sub>		0.45	V	
Output Leakage	—	I <sub>LO</sub>	-10	10	µA	V <sub>OUT</sub> = -0.1V to Vcc +0.1V
Output Capacitance	—	C <sub>OUT</sub>	—	12	pF	V <sub>IN</sub> = 0V; Tamb = 25°C; f = 1 MHz
Power Supply Current, Active	TTL input	I <sub>CC</sub>	—	30	mA	f = 5 MHz (Note 1) Vcc = 5.5V;
Power Supply Current, Standby	TTL input	I <sub>CC(S)TTL</sub>	—	2	mA	$\overline{CE}$ = V <sub>IH</sub> (0°C to +70°C) $\overline{CE}$ = V <sub>IH</sub> (-40°C to +85°C) $\overline{CE}$ = Vcc-0.3 to Vcc +1
	TTL input	I <sub>CC(S)TTL</sub>		3	mA	
	CMOS input	I <sub>CC(S)CMOS</sub>		100	µA	

Note 1: AC power supply current above 5MHz: 1mA/MHz

**TABLE 1-3: READ OPERATION AC CHARACTERISTICS**

Parameter	Symbol	28C17A-15		28C17A-20		28C17A-25		Units	Conditions
		Min	Max	Min	Max	Min	Max		
Address to Output Delay	t <sub>ACC</sub>	—	150	—	200	—	250	ns	$\overline{OE} = \overline{CE} = V_{IL}$
$\overline{CE}$ to Output Delay	t <sub>CE</sub>	—	150	—	200	—	250	ns	$\overline{OE} = V_{IL}$
$\overline{OE}$ to Output Delay	t <sub>OE</sub>	—	70	—	80	—	100	ns	$\overline{CE} = V_{IL}$
$\overline{CE}$ or $\overline{OE}$ High to Output Float	t <sub>OFF</sub>	0	50	0	55	0	70	ns	
Output Hold from Address, $\overline{CE}$ or $\overline{OE}$ , whichever occurs first.	t <sub>OH</sub>	0	—	0	—	0	—	ns	

**FIGURE 1-1: READ WAVEFORMS**



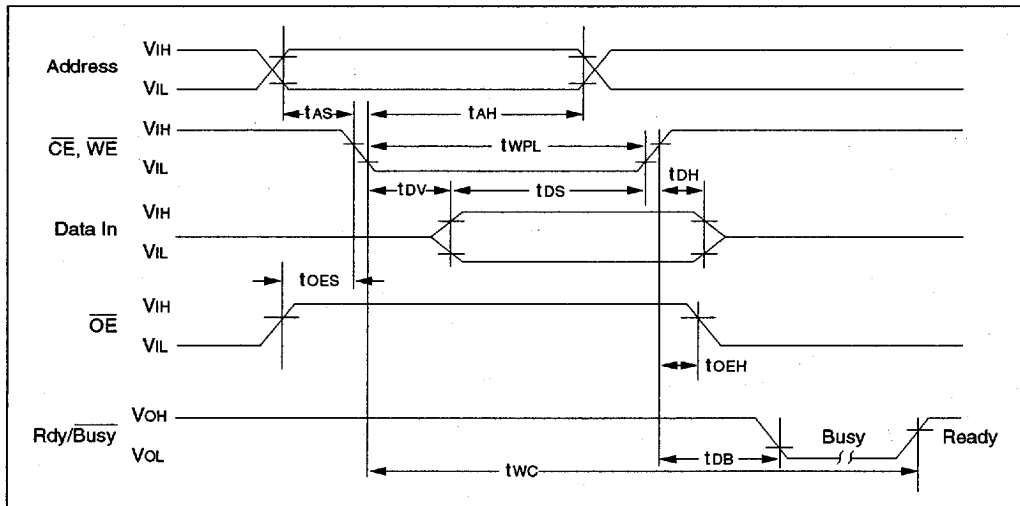
**TABLE 1-4: BYTE WRITE AC CHARACTERISTICS**

Parameter	Symbol	Min	Max	Units	Remarks
Address Set-Up Time	tAS	10	—	ns	
Address Hold Time	tAH	50	—	ns	
Data Set-Up Time	tDS	50	—	ns	
Data Hold Time	tDH	10	—	ns	
Write Pulse Width	twPL	100	—	ns	Note 1
Write Pulse High Time	twPH	50	—	ns	
$\overline{OE}$ Hold Time	tOEH	10	—	ns	
$\overline{OE}$ Set-Up Time	tOES	10	—	ns	
Data Valid Time	tDV	—	1000	ns	Note 2
Time to Device Busy	tDB	2	50	ns	
Write Cycle Time (28C17A)	twc	—	1	ms	0.5 ms typical
Write Cycle Time (28C17AF)	twc	—	200	$\mu$ s	100 $\mu$ s typical

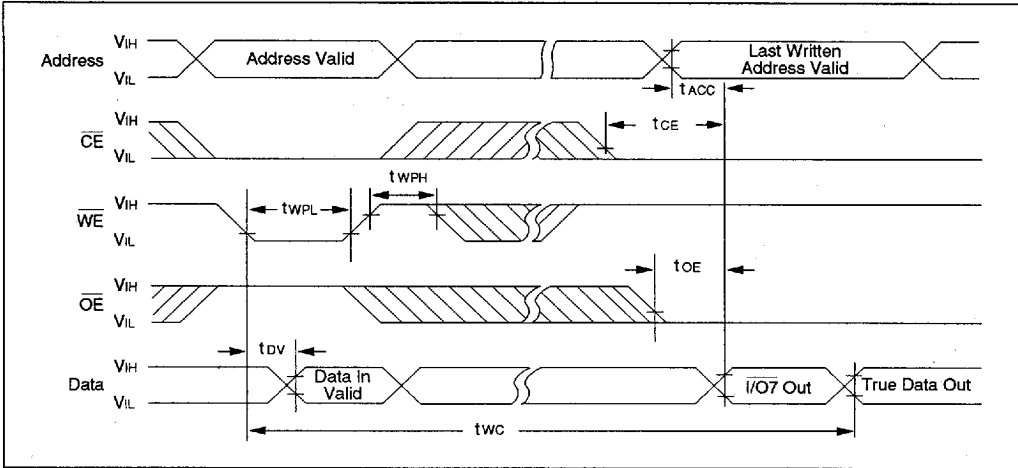
AC Testing Waveform:  
 Output Load:  $V_{IH} = 2.4V$ ;  $V_{IL} = 0.45V$ ;  $V_{OH} = 2.0V$ ;  $V_{OL} = 0.8V$   
 Input Rise/Fall Times: 1 TTL Load + 100 pF  
 20 ns  
 Ambient Temperature: Commercial (C):  $T_{amb} = 0^{\circ}C$  to  $+70^{\circ}C$   
 Industrial (I):  $T_{amb} = -40^{\circ}C$  to  $+85^{\circ}C$

Note 1: A write cycle can be initiated by  $\overline{CE}$  or  $\overline{WE}$  going low, whichever occurs last. The data is latched on the positive edge of  $\overline{CE}$  or  $\overline{WE}$ , whichever occurs first.  
 Note 2: Data must be valid within 1000ns max. after a write cycle is initiated and must be stable at least until tDH after the positive edge of  $\overline{WE}$  or  $\overline{CE}$ , whichever occurs first.

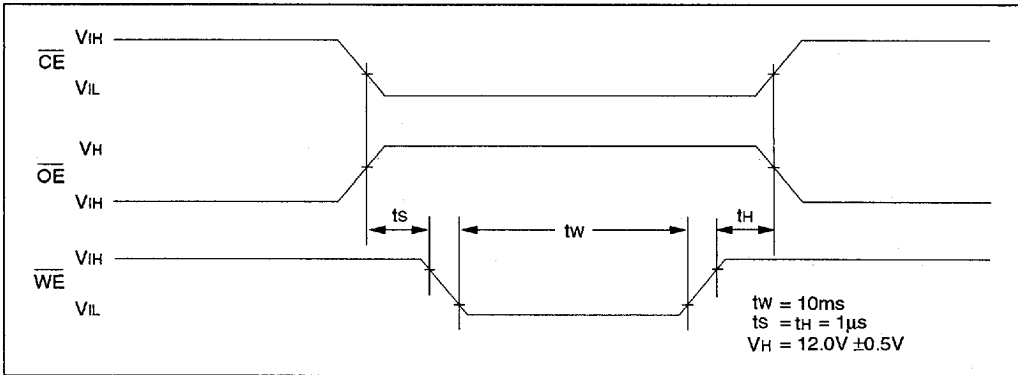
**FIGURE 1-2: PROGRAMMING WAVEFORMS**



**FIGURE 1-3: DATA POLLING WAVEFORMS**



**FIGURE 1-4: CHIP CLEAR WAVEFORMS**



**TABLE 1-5: SUPPLEMENTARY CONTROL**

Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	A9	Vcc	I/O
Chip Clear	V <sub>IL</sub>	V <sub>H</sub>	V <sub>IL</sub>	X	V <sub>cc</sub>	
Extra Row Read	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>H</sub>	A9 = V <sub>H</sub>	V <sub>cc</sub>	Data Out
Extra Row Write	*	V <sub>H</sub>	*	A9 = V <sub>H</sub>	V <sub>cc</sub>	Data In

Note 1: V<sub>H</sub> = 12.0V ±0.5V

\* Pulsed per programming waveforms.

## 2.0 DEVICE OPERATION

The Microchip Technology Inc. 28C17A has four basic modes of operation—read, standby, write inhibit, and byte write—as outlined in the following table.

Operation Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	I/O	Rdy/Busy (1)
Read	L	L	H	DOUT	H
Standby	H	X	X	High Z	H
Write Inhibit	H	X	X	High Z	H
Write Inhibit	X	L	X	High Z	H
Write Inhibit	X	X	H	High Z	H
Byte Write	L	H	L	DIN	L
Byte Clear	Automatic Before Each "Write"				

Note 1: Open drain output.

Note 2: X = Any TTL level.

### 2.1 Read Mode

The 28C17A has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip enable ( $\overline{CE}$ ) is the power control and should be used for device selection. Output Enable ( $\overline{OE}$ ) is the output control and is used to gate data to the output pins independent of device selection. Assuming that addresses are stable, address access time ( $t_{ACC}$ ) equal to the delay from  $\overline{CE}$  to output ( $t_{CE}$ ). Data is available at the output  $\overline{OE}$  after the falling edge of  $\overline{OE}$ , assuming that  $\overline{CE}$  has been low and addresses have been stable for at least  $t_{ACC-tOE}$ .

### 2.2 Standby Mode

The 28C17A is placed in the standby mode by applying a high signal to the  $\overline{CE}$  input. When in the standby mode, the outputs are in a high impedance state, independent of the  $\overline{OE}$  input.

### 2.3 Data Protection

In order to ensure data integrity, especially during critical power-up and power-down transitions, the following enhanced data protection circuits are incorporated:

First, an internal Vcc detect (3.3 volts typical) will inhibit the initiation of non-volatile programming operation when Vcc is less than the Vcc detect circuit trip.

Second, there is a  $\overline{WE}$  filtering circuit that prevents  $\overline{WE}$  pulses of less than 10 ns duration from initiating a write cycle.

Third, holding  $\overline{WE}$  or  $\overline{CE}$  high or  $\overline{OE}$  low, inhibits a write cycle during power-on and power-off (Vcc).

### 2.4 Write Mode

The 28C17A has a write cycle similar to that of a Static RAM. The write cycle is completely self-timed and initiated by a low going pulse on the  $\overline{WE}$  pin. On the falling edge of  $\overline{WE}$ , the address information is latched. On rising edge, the data and the control pins ( $\overline{CE}$  and  $\overline{OE}$ ) are latched. The Ready/Busy pin goes to a logic low level indicating that the 28C17A is in a write cycle which signals the microprocessor host that the system bus is free for other activity. When Ready/Busy goes back to a high, the 28C17A has completed writing and is ready to accept another cycle.

### 2.5 Data Polling

The 28C17A features Data polling to signal the completion of a byte write cycle. During a write cycle, an attempted read of the last byte written results in the data complement of I/O7 (I/O0 to I/O6 are indeterminate). After completion of the write cycle, true data is available. Data polling allows a simple read/compare operation to determine the status of the chip eliminating the need for external hardware.

### 2.6 Electronic Signature for Device Identification

An extra row of 32 bytes of EEPROM memory is available to the user for device identification. By raising A9 to 12V  $\pm$  0.5V and using address locations 7E0 to 7FF, the additional bytes can be written to or read from in the same manner as the regular memory array.

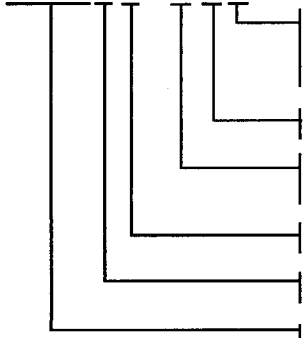
### 2.7 Chip Clear

All data may be cleared to 1's in a chip clear cycle by raising  $\overline{OE}$  to 12 volts and bringing the  $\overline{WE}$  and  $\overline{CE}$  low. This procedure clears all data, except for the extra row.

# 28C17A

## 28C17A Product Identification System

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

28C17A F T - 15 I / P	
	<b>Package:</b>
	J = CERDIP L = Plastic Leaded Chip Carrier (PLCC) P = Plastic DIP TS = Thin Small Outline Package (TSOP) 8x20mm VS = Very Small Outline Package (VSOP) 8x13.4mm
	<b>Temperature Range:</b>
	Blank = 0°C to +70°C I = -40°C to +85°C
	<b>Access Time:</b>
	15 150 ns 20 200 ns 25 250 ns
<b>Shipping:</b>	
Blank Tube T Tape and Reel "L" and "SO"	
<b>Option:</b>	
- = twc = 1ms F = twc = 200 μs	
<b>Device:</b>	
28C17A 2K x 8 CMOS EEPROM	

## Sales and Support

Products supported by a preliminary Data Sheet may possibly have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (602) 786-7277
3. The Microchip's Bulletin Board, via your local CompuServe number (CompuServe membership NOT required).

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

For latest version information and upgrade kits for Microchip Development Tools, please call 1-800-755-2345 or 1-602-786-7302.